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## ELECTRONIC COMPONENT AND METHOD OF MANUFACTURE

## Abstract of the Disclosure

5           An electronic component includes a substrate (210, 1510), a device (221, 222) supported by the substrate and including a first bond pad (223, 224, 225, 226), and a cap (231, 232, 631, 731, 732, 1531, 1532) overlying the substrate. The cap includes a second bond pad (241, 242, 243, 244) at an outside surface of the cap, a third bond pad (245, 246, 247, 248) at an inside surface of the cap and electrically  
10   coupled to the first bond pad, and an electrically conductive via (251, 252, 254, 751, 752, 753, 754) extending through the cap and electrically coupling together the second and third bond pads.

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